AMENDMENTS TO THE CLAIMS

A complete listing of all claims as pending in the application with requested amendments is provided below.

1. (Previously presented)A dew-point cooler comprising a heat exchange element, the dew-point cooler being adapted to be operable in counter flow so that when in use a product air stream flows over a first side of the heat exchange element and is cooled by heat transfer to the element and a portion of the product air stream is diverted back over a second side of the heat exchange element, in use the second side of the heat exchange element being provided with a supply of water whereby heat transfer from the heat exchange element to the water causes it to evaporate into the air stream; wherein the heat exchange element comprises a heat conducting wall and a formed heat exchange laminate attached to the heat conducting wall, the formed heat exchange laminate comprising a formable carrier layer at least partially covered with a flexible liquid retaining layer having an open structure such that in use, a heat exchange medium can directly contact the carrier layer through the open structure of the liquid retaining layer.
2. (Previously presented) The dew-point cooler according to claim 1, wherein the liquid retaining layer is a fibrous material and the open structure comprises spaces between the fibres.
3. (Previously presented) The dew-point cooler according to claim 2, wherein the fibrous material is adhered to the carrier layer by an adhesive.
4. (Previously presented) The dew-point cooler according to claim 3, wherein the fibrous material comprises a bonded mixture of polyester and viscose fibres.
5. (Previously presented) The dew-point cooler according to claim 3, wherein the fibrous material comprises a woven or knitted fibrous layer.
6. (Previously presented) The dew-point cooler according to claim 1 wherein the carrier layer comprises aluminium.
7. (Previously presented) The dew-point cooler according to claim 1 wherein the liquid retaining layer has an average thickness of less than 50 microns.
8. (Cancelled)

9. (Previously presented) The dew-point cooler according to claim 1 , wherein the heat exchange laminate is corrugated to form a series of elongate fins.

10. (Previously presented) The dew-point cooler according to claim 9 wherein the elongate fins are wave shaped in their elongate direction.

11. (Previously presented) The dew-point cooler according to claim 9, wherein the fins are provided with louvres.

12. (Previously presented) The dew-point cooler according to claim 1 , wherein the liquid retaining layer is provided substantially only on a first side of the carrier layer.

13. (Cancelled)

14. (Previously presented) The dew-point cooler according to claim 1 wherein the formed heat exchange laminate is attached to the heat conducting wall by adhesive.

15. (Previously presented) The dew-point cooler according to claim 14 wherein the adhesive is a heat actuated adhesive applied to the carrier layer or the heat conducting wall.

16. (Previously presented) The dew-point cooler according to claim 1 wherein the heat conducting wall is formed into a tubular structure.

17. (Previously presented) The dew-point cooler according to claim 1, wherein the heat conducting wall also comprises a heat exchange laminate according to claim 1.

18. (Cancelled)

19. (Cancelled)

20. (Cancelled)

21. (Previously presented) The dew-point cooler according to claim 1, configured for use in a method of manufacturing comprising:

providing the heat exchange laminate comprising the formable carrier layer at least partially covered with the flexible liquid retaining layer having the open structure;

forming the laminate into a plurality of elongate fins; and

attaching the fins to the heat conducting wall for heat transfer thereto to form the heat exchange element.

22. (Cancelled)

23. (Previously presented) The method according to claim 21 further comprising forming louvres in the fins.

24. (Currently amended) The method according to ~~claim 22~~ claim 21, further comprising attaching the fins to a first surface of ~~a membrane~~ the heat conducting wall for heat transfer thereto.

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25. (Currently amended) The method according to claim 24 further comprising attaching further fins to a second surface of the ~~membrane~~ heat conducting wall for heat transfer thereto.

26. (Currently amended) The method according to claim 25 further comprising folding the ~~membrane~~ heat conducting wall to form a tubular structure with the elongate fins on an exterior surface of the tubular structure and the further fins on an internal surface of the tubular structure.

27. (Previously presented) The dew-point cooler according to claim 10 wherein the liquid retaining layer is provided substantially only on a first side of the carrier layer.

28. (Previously presented) A dew-point cooler comprising a heat exchange element, the dew-point cooler being adapted to be operable in counter flow so that in use air flows over a first side of the heat exchange element and is cooled by heat transfer to the element and air flows over the second side of the element, in use the second side of the heat exchange element being provided with a supply of water whereby heat transfer from the heat exchange element to the water causes it to evaporate into the air stream; wherein the heat exchange element comprises a formed heat exchange laminate having a formable carrier layer at least partially covered with a flexible liquid retaining layer having an open structure such that in use, a heat exchange medium can directly contact the carrier layer through the open structure of the liquid retaining layer.

29. (Previously presented) A dew point cooler comprising a heat exchange element; the heat exchange element comprising

i) a first side forming a flowpath for an airstream;

ii) a second side forming ~~an~~ a flowpath for an airstream; and

iii) a heat exchange laminate comprising a formable carrier layer at least partially covered with a flexible liquid retaining layer having an open structure such that in use, a heat exchange medium can directly contact the carrier layer through the open structure of the liquid retaining layer.